

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A solid state lamp comprising:  
a light emitting element;  
a mounting area adapted to contain the light emitting element;  
and,  
a suspension media disposed between said mounting area and  
said light emitting element which supportably surrounds the light emitting element  
within the mounting area.
2. (Original) The solid state lamp as set forth in claim 1, wherein the  
suspension media comprises a substantially optically transparent material.
3. (Original) The solid state lamp as set forth in claim 1, wherein the  
suspension media includes a first layer disposed between the mounting area and the  
light emitting element, the suspension media further comprising:  
a second layer covering the light emitting element and the first layer.
4. (Original) The solid state lamp as set forth in claim 3, wherein  
selected ones of the first layer and the second layer comprise a thermally conductive  
filler.
5. (Original) The solid state lamp as set forth in claim 3, wherein  
selected ones of the first layer and the second layer comprise phosphor.
6. (Currently Amended) The solid state lamp as set forth in claim 3,  
further comprising a third layer disposed between the light emitting diode element and  
the second layer.

7. (Original) The solid state lamp as set forth in claim 4, wherein the thermally conductive filler comprises at least one nano-particle selected from the set of gold and silver.

8. (Original) The solid state lamp as set forth in claim 3, wherein at least one of the first layer and the second layer comprise single crystal nano-particles.

9. (Original) The solid state lamp as set forth in claim 3, wherein at least one of the first layer and the second layer comprise dielectric nano-particles.

10. (Withdrawn) A method of manufacturing a solid state lamp comprising:

locating a suspension media in a mounting area, where a volume of the mounting area exceeds a volume of the suspension media;  
at least partially curing the suspension media; and,  
supporting a light emitting device with the suspension media.

11. (Withdrawn) The method of manufacturing a solid state lamp as set forth in claim 10, further comprising affixing electrical leads to the light emitting device.

12. (Withdrawn) The method of manufacturing a solid state lamp as set forth in claim 11, further comprising depositing a phosphor layer over the light emitting device.

13. (Withdrawn) The method of manufacturing a solid state lamp as set forth in claim 11, further comprising depositing a phosphor embedded suspension layer over the light emitting device and the suspension media.

14. (Currently Amended) A photonic device comprising:  
a mounting area;  
a spacing element which spaces a semiconductor device from the mounting area; ~~and,~~  
means for affixing the semiconductor device substantially within the mounting area; ~~and,~~  
where the spacing element includes an optically transparent media disposed between the mounting area and the semiconductor device.

15. (Canceled)

16. (Currently Amended) The photonic device as set forth in claim ~~15~~ 14, where the optically transparent media disposed between the mounting area and the semiconductor device comprises silicone epoxy blended with phosphor particles.

17. (Currently Amended) The photonic device as set forth in claim ~~15~~ 14, where the optically transparent media disposed between the mounting area and the semiconductor device comprises silicone epoxy blended with thermally conductive fillers.

18. (Original) The photonic device as set forth in claim 14, where the affixing the semiconductor device substantially within the mounting area includes an optically transparent media disposed over the semiconductor device and the spacing element.

19. (Original) The photonic device as set forth in claim 18 further comprising a phosphor layer disposed over the semiconductor device between the spacing element and the means for affixing the semiconductor device.